

## Product Summary

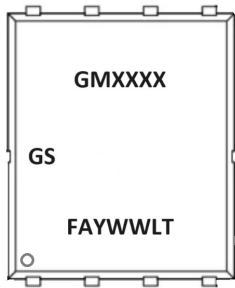
| $V_{DS}$ (V) | $R_{DS(on),max}$ (mΩ) | $I_D$ (A)         |
|--------------|-----------------------|-------------------|
| 30           | 8.8 @ $V_{GS} = 10V$  | 50 <sup>(1)</sup> |

## Features

- Low  $R_{DS(on)}$  trench technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

## Application

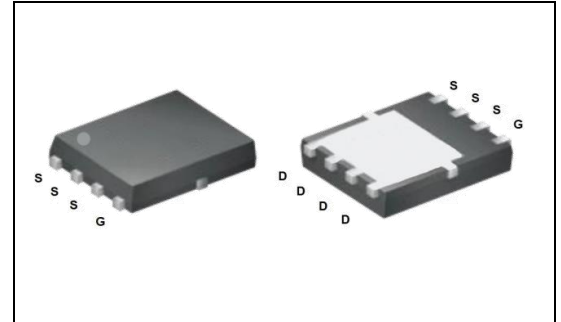
- DC/DC conversion
- Power switch
- Motor drives
- Li- Battery Protection



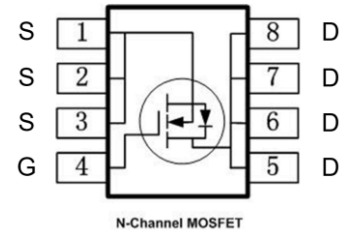
PDFN3333

NOTE:  
 LOGO - GS  
 GMXXXXX- Part number code  
 F - Fab location code  
 A - Assembly location code  
 Y - Year code  
 WW - Week code  
 L&T - Assembly lot code

PDFN3333



Equivalent circuit



## Absolute maximum rating@25°C

| Parameter                                        |                                      | Symbol                            | Limit      | Unit |
|--------------------------------------------------|--------------------------------------|-----------------------------------|------------|------|
| Drain-source voltage                             |                                      | V <sub>DS</sub>                   | 30         | V    |
| Gate-source voltage                              |                                      | V <sub>GS</sub>                   | ±20        |      |
| Continuous drain current                         | T <sub>C</sub> =25°C <sup>(1)</sup>  | I <sub>D</sub>                    | 50         | A    |
|                                                  | T <sub>C</sub> =100°C <sup>(1)</sup> |                                   | 37         |      |
| Pulsed drain current <sup>2</sup>                |                                      | I <sub>D,pulse</sub>              | 100        |      |
| Avalanche energy, single pulse <sup>3</sup>      |                                      | E <sub>AS</sub>                   | 34         | mJ   |
| Power dissipation <sup>4</sup>                   | T <sub>C</sub> =25°C                 | P <sub>D</sub>                    | 26         | W    |
| Operating junction and storage temperature range |                                      | T <sub>J</sub> , T <sub>stg</sub> | -55 to 150 | °C   |

## Thermal Characteristic

| Parameter                                            | Symbol          | Max. | Unit |
|------------------------------------------------------|-----------------|------|------|
| Thermal resistance, junction-to-case <sup>1</sup>    | $R_{\theta JC}$ | 4.7  | °C/W |
| Thermal resistance, junction-to-ambient <sup>1</sup> | $R_{\theta JA}$ | 70   |      |

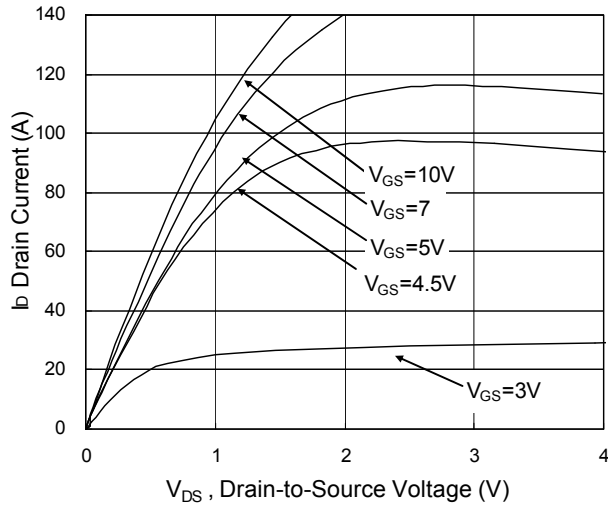
**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

| Parameter                                    | Symbol               | Test conditions                                                                                 | Min. | Typ. | Max. | Unit |
|----------------------------------------------|----------------------|-------------------------------------------------------------------------------------------------|------|------|------|------|
| Static parameter                             |                      |                                                                                                 |      |      |      |      |
| Drain to source breakdown voltage            | V <sub>(BR)DSS</sub> | V <sub>GS</sub> = 0, I <sub>D</sub> = 250 μA                                                    | 30   |      |      | V    |
| Gate-source threshold voltage                | V <sub>GS(th)</sub>  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                                     | 1.1  | 1.5  | 1.9  | V    |
| Gate-body leakage                            | I <sub>GSS</sub>     | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V                                                  |      |      | ±100 | nA   |
| Zero gate voltage drain current              | I <sub>DSS</sub>     | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V                                                   |      |      | 1    | μA   |
| Drain-source on-resistance                   | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A                                                   |      | 6.3  | 8.8  | mΩ   |
|                                              | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 30 A                                                  |      | 8.2  | 11   | mΩ   |
| Forward transconductance <sup>(5)</sup>      | g <sub>fs</sub>      | V <sub>DS</sub> = 5 V, I <sub>D</sub> = 30 A                                                    |      | 40   |      | S    |
| Gate resistance                              | R <sub>g</sub>       | f = 1 MHz                                                                                       |      | 3.3  |      | Ω    |
| Dynamic <sup>(5)</sup>                       |                      |                                                                                                 |      |      |      |      |
| Total gate charge V <sub>GS</sub> = 10V      | Q <sub>g</sub>       | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A, V <sub>GS</sub> = 10 V                           |      | 10   |      | nC   |
| Gate-source charge                           | Q <sub>gs</sub>      |                                                                                                 |      | 3.5  |      |      |
| Gate-drain charge                            | Q <sub>gd</sub>      |                                                                                                 |      | 4.2  |      |      |
| Turn-on delay time                           | t <sub>d(on)</sub>   | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 1 A, V <sub>GS</sub> = 10 V,<br>R <sub>GEN</sub> = 6 Ω |      | 9    |      | ns   |
| Rise time                                    | t <sub>r</sub>       |                                                                                                 |      | 11   |      |      |
| Turn-off delay time                          | t <sub>d(off)</sub>  |                                                                                                 |      | 29   |      |      |
| Fall time                                    | t <sub>f</sub>       |                                                                                                 |      | 7    |      |      |
| Input capacitance                            | C <sub>iss</sub>     | V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz                                        |      | 1200 |      | pF   |
| Output capacitance                           | C <sub>oss</sub>     |                                                                                                 |      | 185  |      |      |
| Reverse transfer capacitance                 | C <sub>rss</sub>     |                                                                                                 |      | 113  |      |      |
| Reverse Diode Characteristics <sup>(5)</sup> |                      |                                                                                                 |      |      |      |      |
| Diode forward voltage                        | V <sub>SD</sub>      | V <sub>GS</sub> = 0 V, I <sub>F</sub> = 2 A                                                     |      | 0.7  | 1.2  | V    |
| Reverse recovery time                        | t <sub>rr</sub>      | I <sub>F</sub> = 15 A, di/dt = 100 A/μs                                                         |      | 15   |      | ns   |
| Reverse recovery charge                      | Q <sub>rr</sub>      |                                                                                                 |      | 7    |      | nC   |

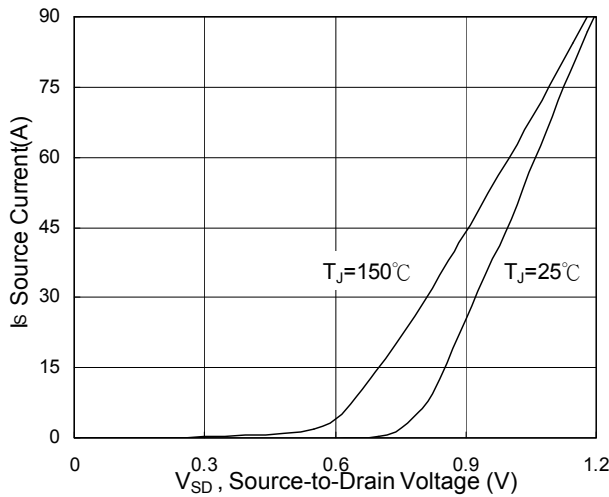
**Notes**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t<sub>s</sub> ≤ 10sec.
2. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
3. The E<sub>AS</sub> data shows Max. rating. The test condition is V<sub>DD</sub> = 25V, V<sub>GS</sub> = 10V, L = 0.1mH, I<sub>AS</sub> = 26A
4. The power dissipation is limited by 150°C junction temperature.
5. Guaranteed by design, not subject to production testing.

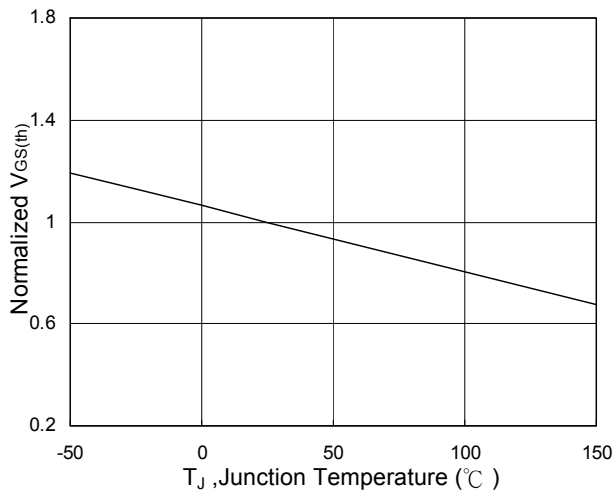
## Typical Performance Characteristics



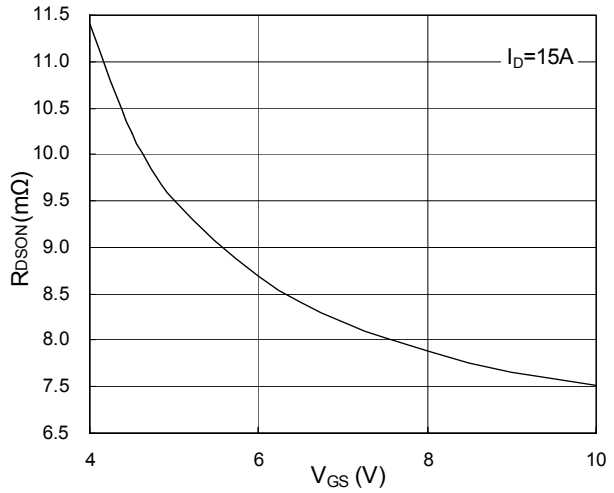
**Fig.1 Typical Output Characteristics**



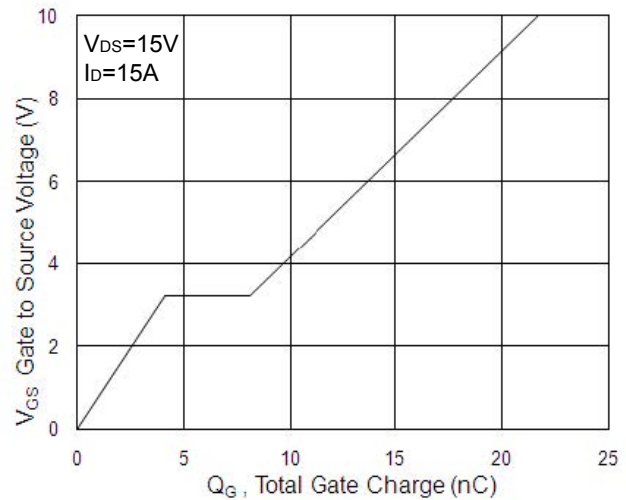
**Fig.3 Forward Characteristics of Reverse**



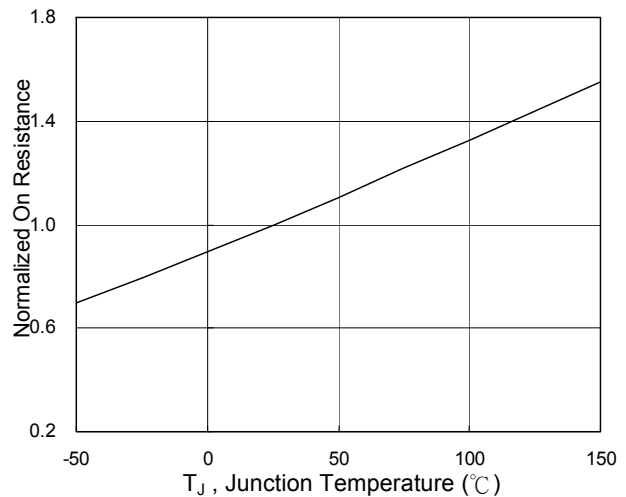
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.2 On-Resistance vs. Gate-Source**



**Fig.4 Gate-Charge Characteristics**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

## Typical Performance Characteristics

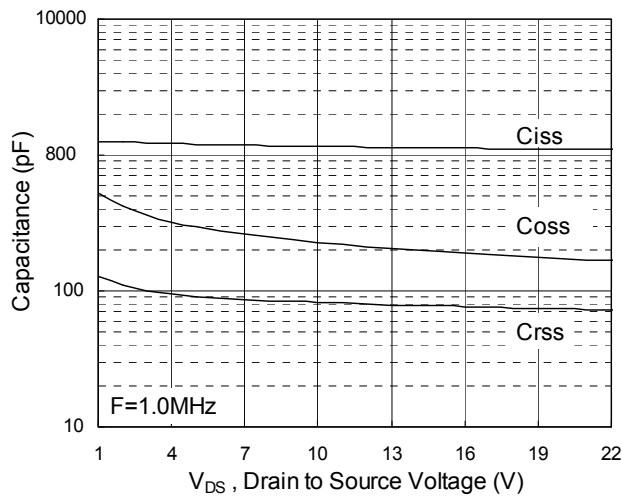


Fig.7 Capacitance

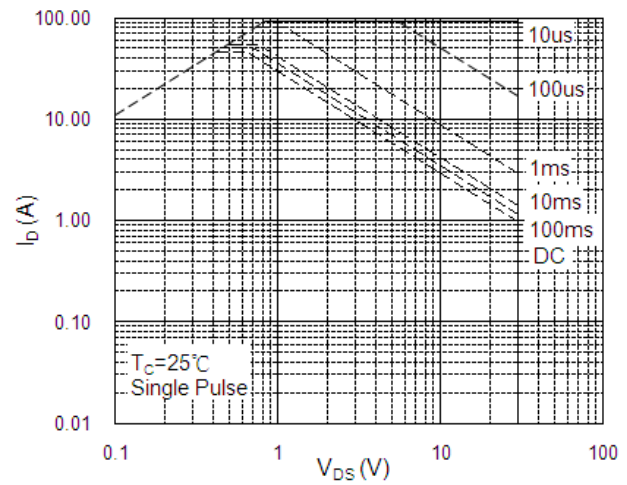


Fig.8 Safe Operating Area

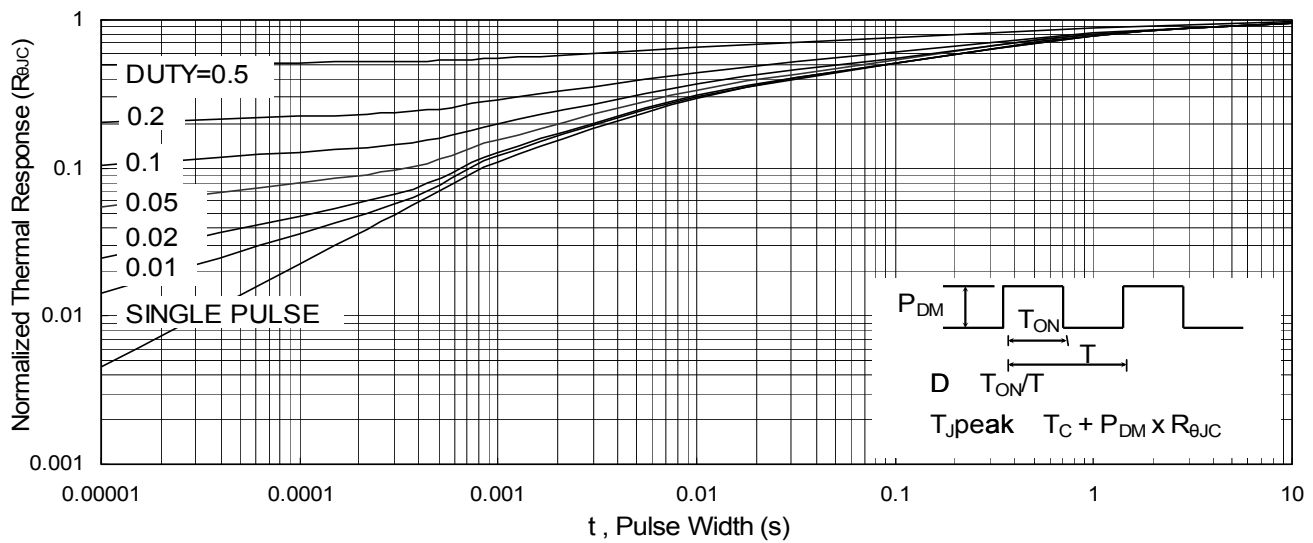
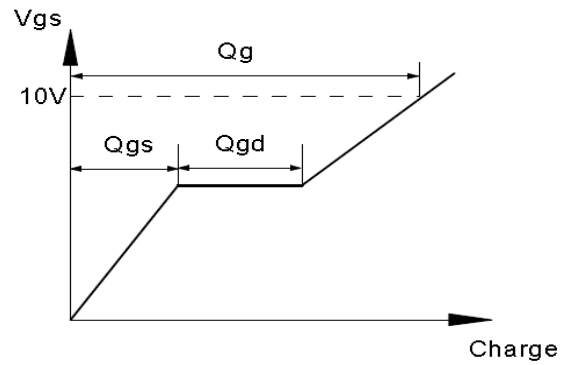
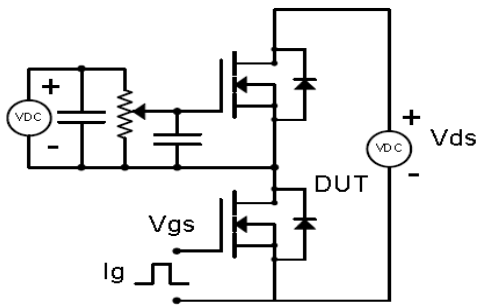


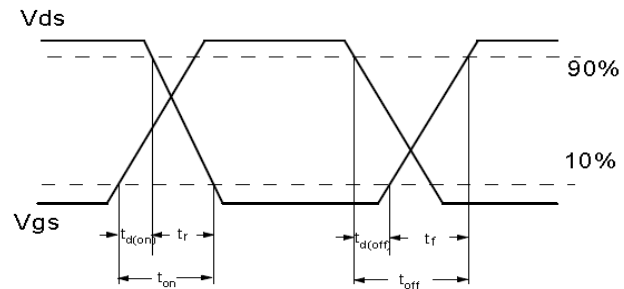
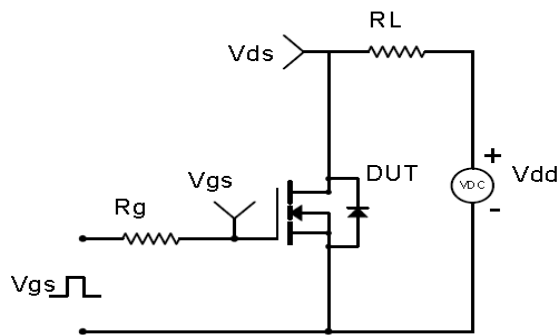
Fig.9 Normalized Maximum Transient Thermal Impedance

## Test Circuit & Waveform

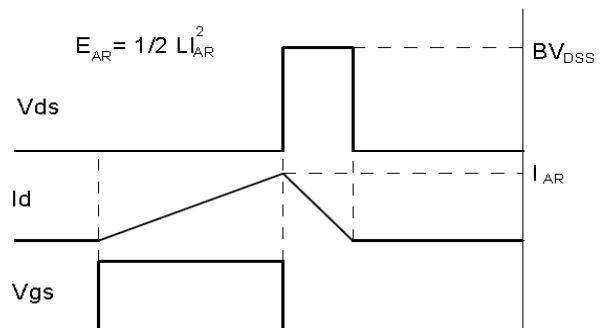
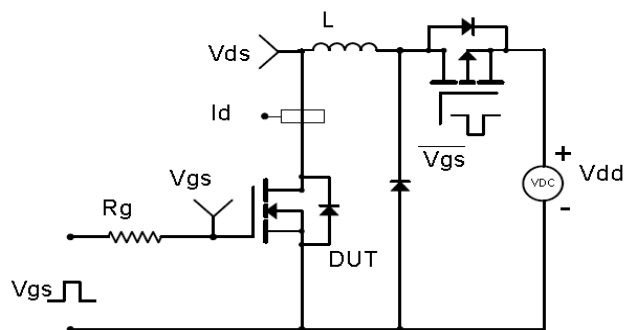
Gate Charge Test Circuit & Waveform



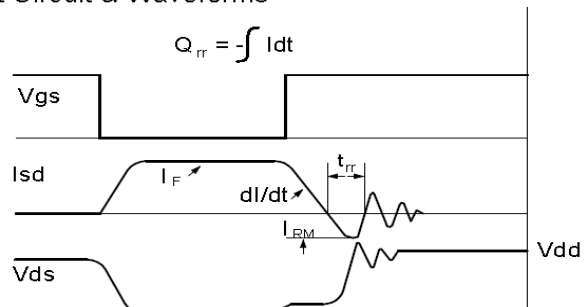
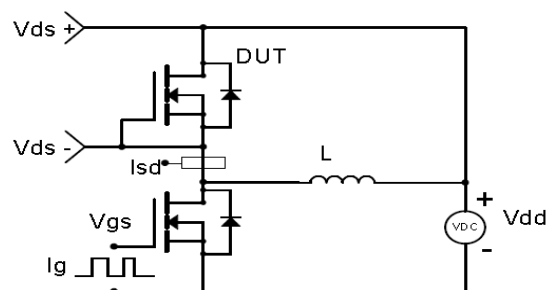
Resistive Switching Test Circuit & Waveforms

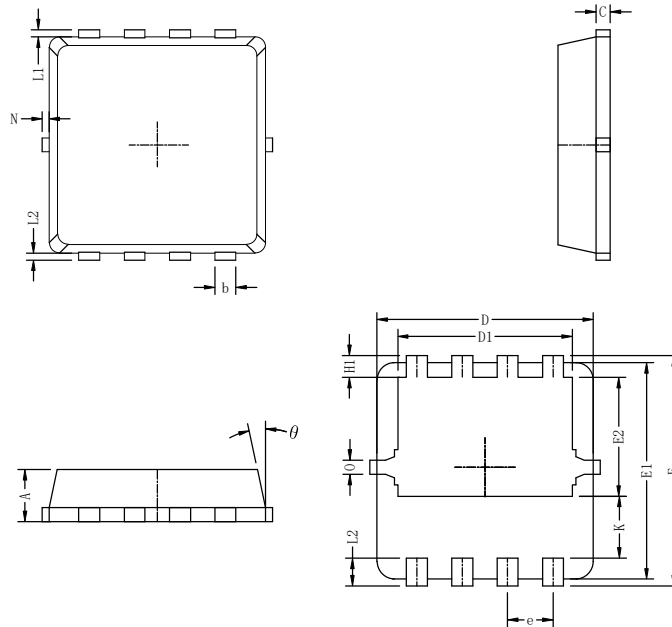


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



**Outline Drawing PDFN3333**


| Symbols | Millimeters |      |      |
|---------|-------------|------|------|
|         | MIN.        | NOM. | MAX. |
| A       | 0.65        | 0.75 | 0.85 |
| b       | 0.25        | 0.30 | 0.35 |
| C       | 0.15        | 0.20 | 0.25 |
| D       | 3.00        | 3.10 | 3.20 |
| D1      | 2.40        | 2.50 | 2.60 |
| E       | 3.20        | 3.30 | 3.40 |
| E1      | 3.00        | 3.10 | 3.20 |
| E2      | 1.60        | 1.70 | 1.80 |
| e       | 0.65 BSC.   |      |      |
| H1      | 0.21        | 0.31 | 0.41 |
| H2      | 0.30        | 0.40 | 0.50 |
| K       | 0.78        | 0.88 | 0.98 |
| L1/L2   | 0.10 REF.   |      |      |
| θ       | 11°         | 12°  | 13°  |
| N       | 0           | -    | 0.15 |
| 0       | 0.2 REF.    |      |      |

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